Listing of Claims:

1-17. (CANCELED)

18. (CURRENTLY AMENDED) An amplifier comprising:

a main amplifier subcircuit and an error amplifier subcircuit each directly mounted together on a single circuit board;

a chassis body;

a lid structure for positioning with the chassis body to contain the circuit board and main and error amplifier subcircuits;

one of the lid structure and the chassis body having generally solid side walls extending therefrom for defining a main amplifier cavity with subcavities to contain subcircuits of the main amplifier subcircuit and an error amplifier cavity with subcavities to contain subcircuits of the error amplifier subcircuit, the side walls extending to contact the circuit board to isolate the subcircuits;

the one of the lid structure and chassis body further including a generally solid dividing wall, of greater thickness than the side walls, extending between the main amplifier subcircuit and the error amplifier subcircuit, the dividing wall having multiple broad islands extending therefrom, the multiple islands passing through multiple cut-outs formed in the circuit board between the main amplifier subcircuit and respective cavity and the error amplifier subcircuit and respective cavity to electrically couple to the other of the lid structure and chassis body to separate the amplifier cavities and electrically isolate the main and error amplifier subcircuits.

19-22. (CANCEL)

23. (PREVIOUSLY PRESENTED) The amplifier of claim 22 wherein the side walls are integrally formed with the lid structure.

24. (PREVIOUSLY PRESENTED) The amplifier of claim 22 wherein the side walls extend from the lid structure and further comprising additional subcircuits, the lid structure including at least one other side wall extending from a side of the lid structure opposite the side wall for isolating subcircuits on both sides of the lid structure.

25. (CANCELED)

26. (PREVIOUSLY PRESENTED) The amplifier of claim 22 further comprising a gasket coupled between the side wall and a circuit board for isolating the subcircuit.

27-32. (CANCELED)

33. (CURRENTLY AMENDED) A method of isolating subcircuits of an amplifier comprising:

mounting each of a main amplifier subcircuit and an error amplifier subcircuit directly on a single circuit board in a chassis body;

positioning a lid structure with the chassis body to contain the circuit board and amplifier subcircuits, at least one of the lid structure and the chassis body having

generally solid side walls extending therefrom for defining a main amplifier cavity with subcavities to contain subcircuits of the main amplifier subcircuit and an error amplifier cavity with subcavities to contain subcircuits of the error amplifier subcircuit;

positioning the single circuit board so that the side walls extend to contact the circuit board to isolate the subcircuits within the main amplifier cavity and the error amplifier cavity;

positioning a generally solid dividing wall, depending from one of the lid structure and the chassis body, between the main amplifier cavity and the error amplifier cavity, the dividing wall having a greater thickness than the side walls;

passing multiple broad islands, extending from the dividing wall, through multiple cut-outs formed in the circuit board between the main amplifier subcircuit and respective cavity and the error amplifier subcircuit and respective cavity to electrically couple to the other of the lid structure and chassis body to separate the amplifier cavities and electrically isolate the main and error amplifier subcircuits.

34 and 35. (CANCELED)

36.(PREVIOUSLY PRESENTED) The method of claim 33 wherein the side walls are integrally formed with the lid structure.

37.(PREVIOUSLY PRESENTED) The method of claim 33 wherein the side walls extend from the lid structure and the lid structure includes at least one other side wall extending from a side of the lid structure opposite the other side walls, and further comprising

positioning additional subcircuits proximate the one other side for isolating subcircuits on both sides of the lid structure.

38.(PREVIOUSLY PRESENTED) The method of claim 33 further comprising coupling a gasket between the side wall and a circuit board for isolating the subcircuit.

39. (CURRENTLY AMENDED) An amplifier comprising:

a main amplifier subcircuit and an error amplifier subcircuit each directly mounted together on a single circuit board;

a chassis body;

a lid structure for positioning with the chassis body to contain the circuit board and main and error amplifier subcircuits;

the lid structure having generally solid side walls extending therefrom for defining a main amplifier cavity with subcavities to contain subcircuits of the main amplifier subcircuit and an error amplifier cavity with subcavities to contain subcircuits of the error amplifier subcircuit, the side walls extending to contact the circuit board to isolate the subcircuits;

the lid structure further including a generally solid dividing wall, of greater thickness than the side walls, extending between the main amplifier subcircuit and the error amplifier subcircuit, the dividing wall having multiple islands extending therefrom, the multiple islands passing through multiple cut-outs formed in the circuit board between the main amplifier subcircuit and respective cavity and error amplifier

subcircuit and respective cavity to electrically couple to the chassis body to separate the amplifier cavities and electrically isolate the main and the error amplifier subcircuits.